

## Appli-Thane® 7300

## 2.5 W/mK Thermally Conductive Urethane Adhesive for Aerospace Applications

The cured material's ability to not crack or harm bonded rigid components during thermal cycling is a major plus. A blue, one-component material, Appli-Thane® 7300 is also used in manufacturing and automated dispensing applications due to its 4-hour pot life. The material is self-leveling and injectable, making it suitable for electronic bonding and potting, as well as bonding leaded components and heat sinks. Appli-Thane® 7300 cures to a semi-flexible material with relatively low modulus and a very low Glass Transition Temperature (Tg). The material is a precision mixed, degassed and frozen compound that provides best-in-class thermal conductivity for applications requiring aggressive heat dissipation of components.

UNCURED		
Work Life	4 hours @ 25°C	
Viscosity	Paste @ 25°C	
Shelf Life	6 months @ -40°C 9 months @ -60°C	
CURE OPTIONS	2 hours @ 96°C 4 hours @ 72°C 2 weeks @ 25°C	
CURED PROPERTIES	Based on cure of 2 hours @ 96°C	
Color	Blue	
Shore A Hardness	95	
Shore D Hardness	45	
Glass Transition Temp (°C)	-40	
Density (g/cc)	2.8	
Lap Shear 2024T3 Clad (psi)	500	
Tensile Strength (psi)	450	
Tensile Modulus (psi)	9,500	
Compressive Strength (psi)	1,400	
Compressive Modulus (psi)	14,500	
Elongation (%)	5	
Poisson's Ratio	0.38	
ELECTRICAL PROPERTIES	Based on cure of 2 hours @ 96°C	
Dielectric Constant	16 @ 10 kHz	
Dissipation Factor	0.00 @ 10 kHz	
Dielectric Strength (volts/mil)	650	
Volume Resistivity (ohm-cm)	1.0E 13 @ 400 VDA	
THERMAL PROPERTIES	Based on cure of 2 hours @ 96°C	
CTE below Tg (ppm/°C)	25	
CTE above Tg (ppm/°C)	75	
Glass Transition Temp (°C)	-40	
Operating Temp. Range (°C)	-100 to 160	
Thermal Conductivity (W/mK)	2.5	
OUTGASSING PROPERTIES	Based on cure of 2 hours @ 96°C	
TML (%)	0.19	
CVCM (%)	0.03	
WVR (%)	0.04	
OUTGASSING PROPERTIES	Based on cure of 2 weeks @ 25°C	
TML (%)	0.12	

KEY	FEATURES
High	n Thermal Conductivity
Mee	ets NASA Outgassing Requirements
Elec	trically Insulative
Sem	i-flexible
Supe	erior Thermal Cycling
Hyd	rolytic Stability
Idea	l for Electrical Potting
Injed	ctable
Long	g Pot Life
Low	Glass Transition Temperature
Low	Modulus
Self	Leveling
Solv	ent Resistant

## Talk to an engineer:

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WVR (%)	0.03
ACOUSTIC PROPERTIES	
Velocity (m/s)	2,145
Impedance (MRayles)	6.28
Loss (dB/cm-MHz)	-16.5
Density (g/cc)	2.8